

# MBRB2515L

Preferred Device

## SWITCHMODE™ Power Rectifier ORing Function Diode D<sup>2</sup>PAK Surface Mount Power Package

The D<sup>2</sup>PAK Power Rectifier employs the Schottky Barrier principle in a large metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for use in low voltage, high frequency switching power supplies, free wheeling diodes, and polarity protection diodes.

### Features

- Guardring for Stress Protection
- Low Forward Voltage
- 100°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Short Heat Sink Tab Manufactured – Not Sheared
- Similar in Size to the Industry Standard TO-220 Package
- Pb-Free Packages are Available

### Mechanical Characteristics:

- Case: Epoxy, Molded, Epoxy Meets UL 94 V-0
- Weight: 1.7 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL1 Requirements
- ESD Ratings: Machine Model, C (>400 V)  
Human Body Model, 3B (>8000 V)

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	15	V
Average Rectified Forward Current (Rated $V_R$ , $T_C = 90^\circ\text{C}$ )	$I_{F(AV)}$	25	A
Peak Repetitive Forward Current (Rated $V_R$ , Square Wave, 20 kHz, $T_C = 100^\circ\text{C}$ )	$I_{FRM}$	30	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	$I_{FSM}$	150	A
Storage Temperature Range	$T_{stg}$	-65 to +150	°C
Operating Junction Temperature	$T_J$	100	°C
Voltage Rate of Change (Rated $V_R$ )	$dv/dt$	10,000	V/ $\mu\text{s}$

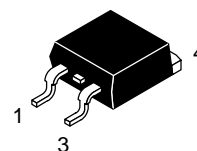
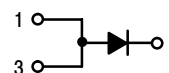
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.



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## SCHOTTKY BARRIER RECTIFIER 25 AMPERES, 15 VOLTS



D<sup>2</sup>PAK  
CASE 418B  
STYLE 3

### MARKING DIAGRAM



A = Assembly Location  
Y = Year  
WW = Work Week  
B2515L = Device Code  
G = Pb-Free Package  
AKA = Diode Polarity

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

**Preferred** devices are recommended choices for future use and best overall value.

# MBRB2515L

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, – Junction-to-Case	$R_{\theta JC}$	1.0	$^{\circ}\text{C/W}$
– Junction-to-Ambient (Note 1)	$R_{\theta JA}$	50	

1. When mounted using minimum recommended pad size on FR-4 board.

## ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 2) ( $I_F = 19$ Amps, $T_J = 70^{\circ}\text{C}$ ) ( $I_F = 25$ Amps, $T_J = 70^{\circ}\text{C}$ ) ( $I_F = 25$ Amps, $T_J = 25^{\circ}\text{C}$ )	$V_F$	0.38 0.42 0.45	V
Maximum Instantaneous Reverse Current (Note 2) (Rated dc Voltage, $T_J = 70^{\circ}\text{C}$ ) (Rated dc Voltage, $T_J = 25^{\circ}\text{C}$ )	$I_R$	200 15	mA

2. Pulse Test: Pulse Width = 300  $\mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

## ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MBRB2515L	D <sup>2</sup> PAK	50 Units / Rail
MBRB2515LG	D <sup>2</sup> PAK (Pb-Free)	50 Units / Rail
MBRB2515LT4	D <sup>2</sup> PAK	800 Units / Tape & Reel
MBRB2515LT4G	D <sup>2</sup> PAK (Pb-Free)	800 Units / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

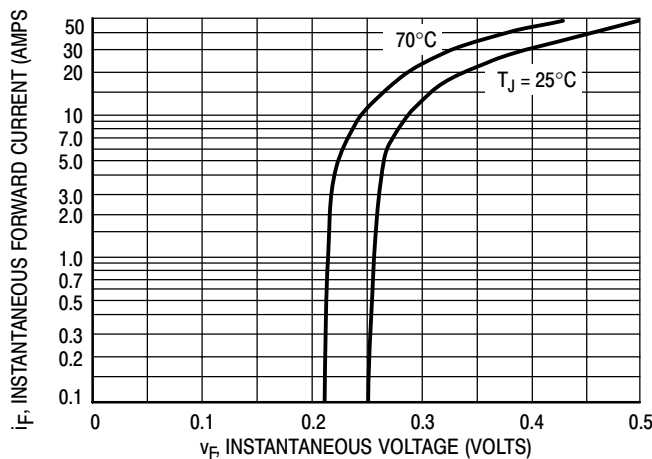


Figure 1. Typical Forward Voltage

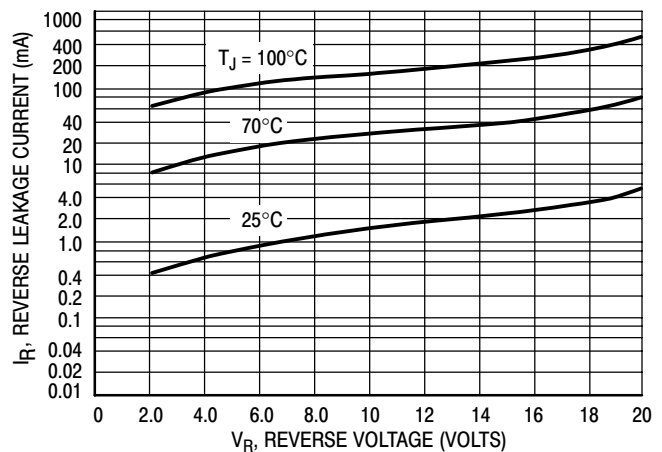


Figure 2. Typical Reverse Leakage Current

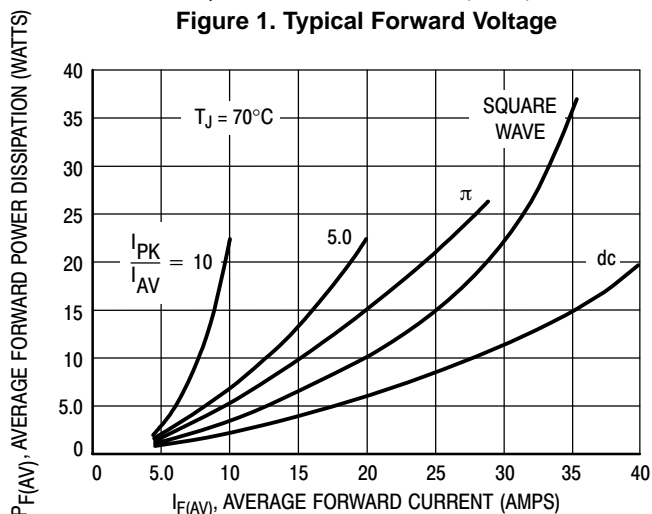


Figure 3. Typical Forward Power Dissipation

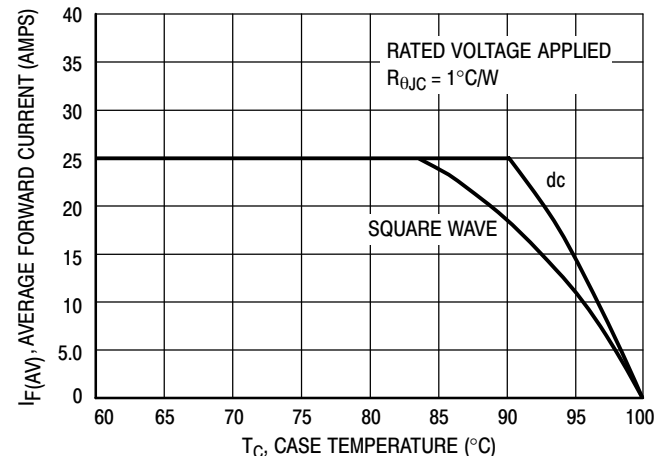
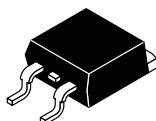


Figure 4. Current Derating, Case

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# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

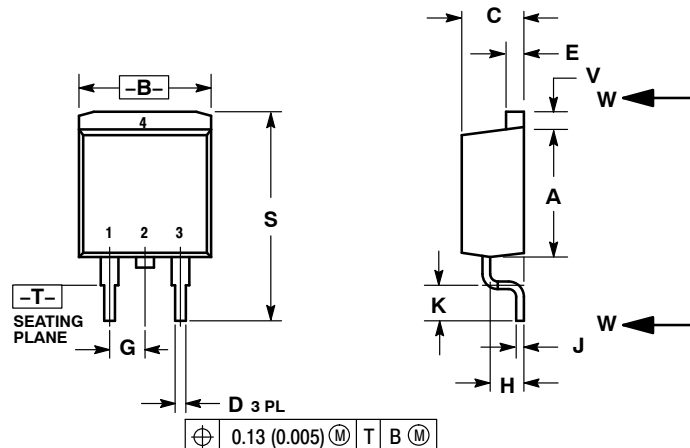
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**D<sup>2</sup>PAK 3**  
CASE 418B-04  
ISSUE L

DATE 17 FEB 2015

SCALE 1:1

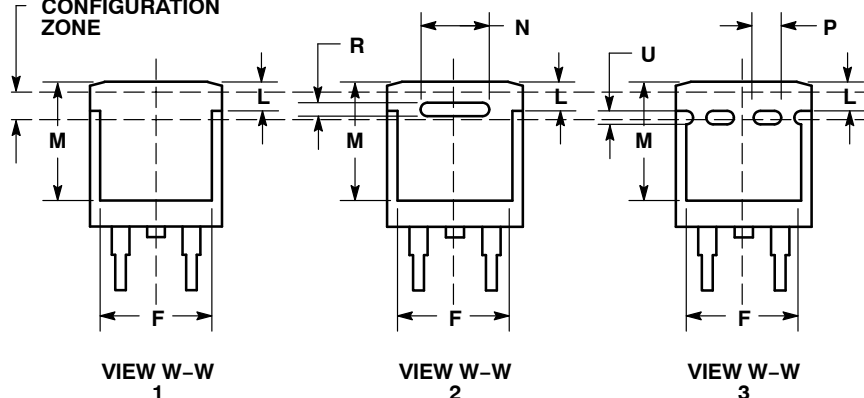


## NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.340	0.380	8.64	9.65
B	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
E	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100	BSC	2.54	BSC
H	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
M	0.280	0.320	7.11	8.13
N	0.197	REF	5.00	REF
P	0.079	REF	2.00	REF
R	0.039	REF	0.99	REF
S	0.575	0.625	14.60	15.88
V	0.045	0.055	1.14	1.40

## VARIABLE CONFIGURATION ZONE



### STYLE 1:

- PIN 1. BASE  
2. COLLECTOR  
3. EMITTER  
4. COLLECTOR

### STYLE 2:

- PIN 1. GATE  
2. DRAIN  
3. SOURCE  
4. DRAIN

### STYLE 3:

- PIN 1. ANODE  
2. CATHODE  
3. ANODE  
4. CATHODE

### STYLE 4:

- PIN 1. GATE  
2. COLLECTOR  
3. EMITTER  
4. COLLECTOR

### STYLE 5:

- PIN 1. CATHODE  
2. ANODE  
3. CATHODE  
4. ANODE

### STYLE 6:

- PIN 1. NO CONNECT  
2. CATHODE  
3. ANODE  
4. CATHODE

## MARKING INFORMATION AND FOOTPRINT ON PAGE 2

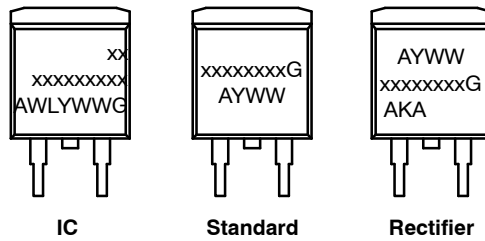
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**D<sup>2</sup>PAK 3**  
CASE 418B-04  
ISSUE L

DATE 17 FEB 2015

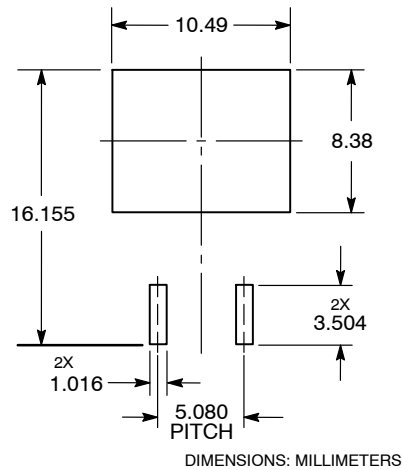
**GENERIC  
MARKING DIAGRAM\***



xx        = Specific Device Code  
A        = Assembly Location  
WL      = Wafer Lot  
Y        = Year  
WW      = Work Week  
G        = Pb-Free Package  
AKA     = Polarity Indicator


\*This information is generic. Please refer to device data sheet for actual part marking.  
Pb-Free indicator, "G" or microdot "▪", may or may not be present.

**SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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